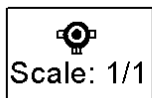
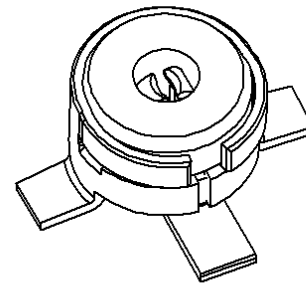
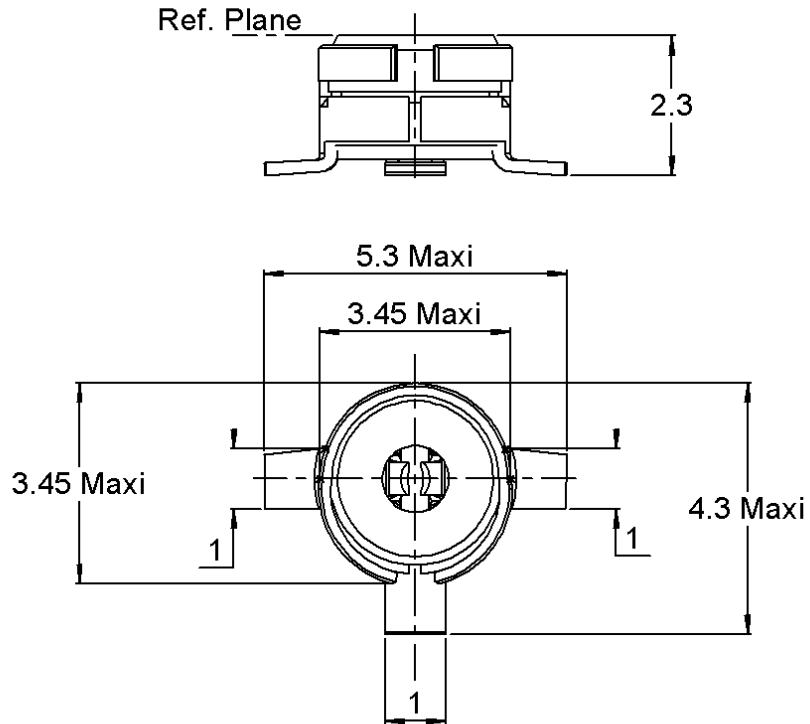
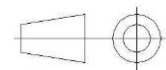


PAGE 1/5	ISSUE 03-02-17B	SERIES MMS	PART NUMBER R209408052
----------	------------------------	-------------------	-------------------------------



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Center contact	BERYLLIUM COPPER	GOLD 0.2 OVER TIN NICKEL 2
Outer contact		
Insulator	PTFE	
Gasket	-	
Others parts	-	
-	-	-
-	-	-

PAGE 2/5	ISSUE 03-02-17B	SERIES MMS	PART NUMBER R209408052
----------	------------------------	-------------------	-------------------------------

PACKAGING

Standard	Unit	Other
500	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-6	GHz
VSWR	* +	0,0000	x F(GHz) Maxi
Insertion loss		**	√F(GHz) dB Maxi
RF leakage	- (NA	- F(GHz) dB Maxi
Voltage rating		50	Veff Maxi
Dielectric withstanding voltage		250	Veff mini
Insulation resistance		500	MΩ mini

ENVIRONMENTAL

Operating temperature	-40/+125	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		NA	N mini
Axial force – Opposite end		NA	N mini
Torque		NA	N.cm mini
Recommended torque			
Mating		NA	N.cm
Panel nut		NA	N.cm
Mating life		50	Cycles mini
Weight		0,0590	g

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

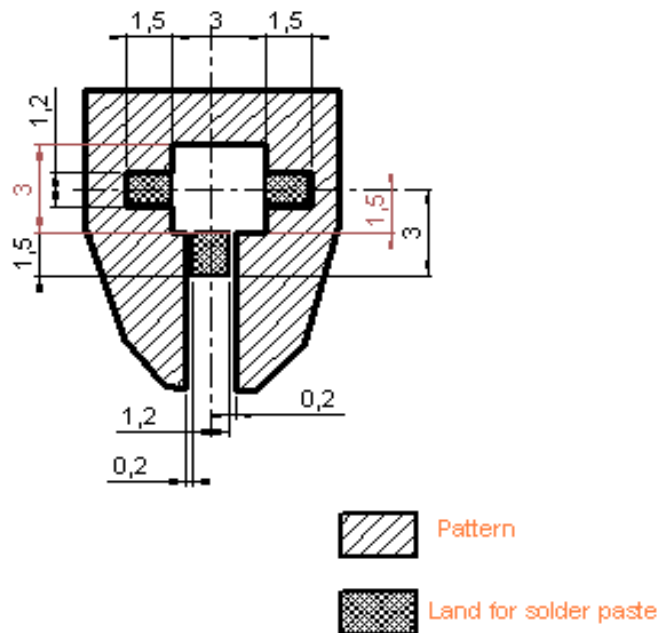
Others:

***1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06**

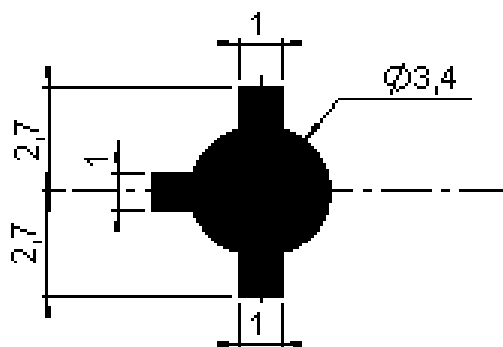
PAGE 3/5	ISSUE 03-02-17B	SERIES MMS	PART NUMBER R209408052
----------	-----------------	------------	------------------------

MMS SERIES – INFORMATION

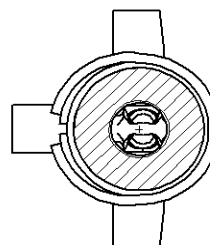
Coplanar line : Ground and signal are on the same side . Thickness of PCB : 1mm
 The material of PCB is glass-epoxy composite. (Er = 4.8)
 The sold er resist should be printed except for the land pattern on the PCB.



SHADOW OF MMS RECEPTACLE FOR VIDEO CAMERA



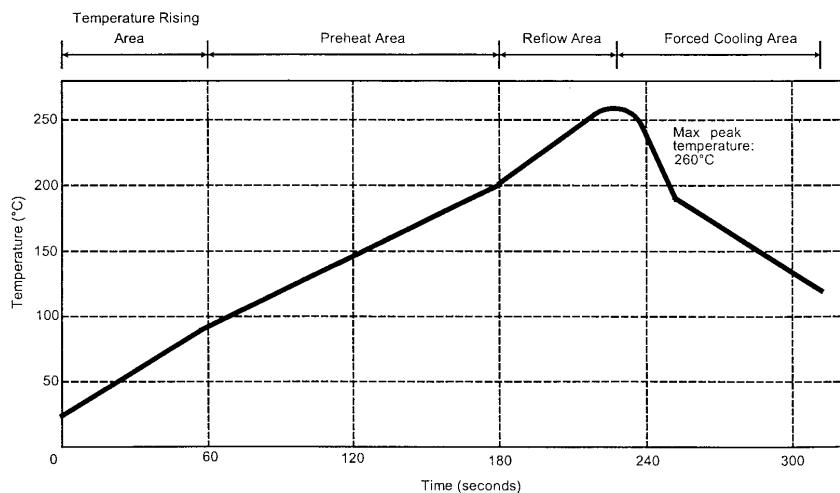
ASPIRATION AREA



SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec